ABSOCIATION CONNECTING ELECTRONICS INDUSTRIES® International and Pan-American	kburn, Illinois, A	Il rights reserved un ntions.	nder both	This docume level parts, t	ent is a declaration en	n of the substar compasses all l	ces within the manufactur ower level materials for w	rer listed ite hich the ma	em. Note: if anufacturer	the item is an as has engineering	sembly with lower responsibility.	
			Form Type * Distribute	* Declaration Class * Class 6 - RoHS Yes/No, Homogeneous Materials and Mfg Information								
Supplier Information												
ompany name* Company unique ID				Unique ID Authority				Response Date*				
onsemi	semi								2024-05-06			
Contact Name	Title - Contact				Phone - Contact*			Email - Contact*				
Product-Env-Stewards	s Product Enviro Compliance			NA				Product-Env-Stewards@onsemi.com				
uthorized Representative* Title - Representative				Phone - Representative*				Email - Representative*				
Product-Env-Stewards Product Enviro Compliance				NA				Product-Env-Stewards@onsemi.com				
Requester Item Number Mfr It	em Number	Mfr Item Name			Effective Date	Version	Manufacturing Site		/eight*	UOM	Unit Type	
NL17:	17SZ10DBVT1G 3-Input NAND Gate		ite		2024-05-06		CN1	1	3.36	mg	Each	
Manufacturing Proccess Information		·			·							
Terminal Plating / Grid Array Material	Terminal Base Alloy J-STD-02		-STD-020 MSL	Rating	Peak Process Body Temperature Max		ature Max Time at Peak	Temperature Number of Reflow Cycles		eles		
Matte Tin (Sn) - annealed CU Alloy 1					260	С	30	second	s 3			
Comments												
evel 1 - maximum time at peak temperature during	soldering is 10-3	0 seconds										
For more information regarding material composition	n please refer to	page 3										

RoHS Material Composition Declaration				Declaration Type *	Detailed					
Directive 2015/863/EU amending RoHS Directive 2011/65/EU	RoHS Definition: Quantity limit of 0.01% by mass (100 PPM) in homogeneous material for Cadmium and quantity limit of 0.1% by mass (1000 PPM) in homogeneous material for: Lead (Pb), Mercury (Hg), Hexavalent Chromium (Cr6+), Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE), and Bis(2-ethylhexyl) phthalate (DEHP), Benzyl-butyl phthalate (BBP), Dibutyl phthalate (DBP), Disobutyl phthalate (DIBP).									
cadmium, hexavalentchromium, polybrominate contains a RoHS restricted substance inexcess encompass all such components. Supplier certif as of the date that Supplier completes this form Company acknowledges that Supplier may hav independently verified information provided by certification in this paragraph. If the Company a	ed biphenyls and/or polybrominated dip of an applicable quantity limit, please ir ies that it gathered the information it pro- .Supplier acknowledges that Company e relied on informationprovided by othe v others, Supplier agrees that, at a minin and the Supplier enter into a written agre pource of the Supplier's liability and the	henyl ethers (each a " ndicate below which, i ovides in this form us will rely on this certifiers in completing this num, itssuppliers have eement with respect to Company's remedies	RoHS restricted substance") in exce if any, RoHS exemption you believe ing appropriate methods to ensure if ication in determining the complian form, and that Supplier may not have e provided certifications regarding the to the identified part, the terms and cc for issues that arise regarding inform	ce of its products with European Union membe	ove. If a homogeneous material within the part er level components, the declaration shall l correct to the best of its knowledge and belief, r state laws that implement the RoHS Directive. wever, in situations where Supplier has not tions are at least as comprehensive as the anty rights and/or remedies provided as part of					
RoHS Declaration * 1 - Item(s)	does not contain RoHS restricted substa	ances per the definitio	on above	Supplier Acceptance	* Accepted					
Exemption: If the declared item does not con applicable exemptions.	ntain RoHS restricted substances per	the definition above	except for defined RoHS exempti	ons, then select the corresponding response i	n the RoHS Declaration above and choose all					
Exemption List Version	EL-2011/534/EU									
Declaration Signature										
Instructions: Complete all of the required fin Requester) and click on Submit Form to have	elds on all pages of this form. Select the form returned to the Requester	he "Accepted" on th	e Supplier Acceptance drop-down	. This will display the signature area. Digital	lly sign the declaration (if required by the					
Supplier Digital Signature Ra	stislav Drska	Le								

Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Substance Instructions: [A] select the Level (JIG A, JIG B, Requester or Supplier) [B] select the substance category (JIG or Requester) or enter a value (Supplier). [C] select the substance (JIG) or enter the substance and CAS (Other). [D] select a RoHS exemption, if applicable [E] enter the weight of the substance or the PPM concentration [F] Optionally enter the positive (+) and negative (-) tolerance in percent (Note: percent tolerance values are expected to cover a 3

sigma range of distribution unless	otherwise noted).							-
Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Die	0.06	mg	Supplier	Silicon (Si)	7440-21-3		0.06	mg
Lead Frame 2.	2.55	mg	В	Nickel (Ni)	7440-02-0		0.9664	mg
			Supplier	Iron (Fe)	7439-89-6		1.3362	mg
			Supplier	Copper (Cu)	7440-50-8		0.2473	mg
Mold Compound-Black	10.61	mg	Supplier	Ortho Cresol Novolac Resin	29690-82-2		1.061	mg
			Supplier	Carbon Black (C)	1333-86-4		0.053	mg
			Supplier	Aluminum Hydroxide (Al(OH)3)	21645-51-2		1.5384	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		6.8965	mg
			Supplier	Phenolic Resin (Novolac)	9003-35-4		1.061	mg
Plating	0.13	mg	Supplier	Tin (Sn)	7440-31-5		0.13	mg
Wire Bond - Cu	0.01	mg	Supplier	Copper (Cu)	7440-50-8		0.01	mg